

# Electronic Manufacturing

Prepared By:



# Electronics manufacturing services (EMS)



- Large assembly house - suitable for high-volume and high-design complexity production.
- Located in Johor Bahru, Malaysia
- New 80,000 sq. ft. facility inaugurated in 2012
- Three high-performance SMT lines
- Extensive RF and telecommunication testing capabilities
- Automated module and box-build lines
- Complete system assembly
- Custom Cable Assemblies



- Small assembly house - suitable for Low to Mid volume project /prototype.
- Located in Old Klang Road, Kuala Lumpur Malaysia
- Minimum chip size component: 0201
- Fine Pitch ICs : pitch less than 0.021"
- BGAs, uBGA, SOICs, SSOPs, QFPs, PLCC, QFN, DFN
- Convection & IR Reflow Solder
- Standard chip size component: 0603 and larger

# Electronics manufacturing services (EMS)



- Large assembly house - suitable for High Mix Low volume project.
- Located in Kulai, Johor Malaysia -9000 sq.ft.
- More than 10 SMT lines.
- Fine pitch placement of up to 0201 (0603) chips.
- Integrated Circuit (IC), QFP, BGA and CSP mounting enabled.
- Facilities: Pick and Place Machine, Encapsulation Machines, Coiling and Reflow Ovens, BGA Rework Stations, Solder Paste Inspection Machines (SPI), X-Ray Inspection Systems

# Electronics manufacturing services (EMS)



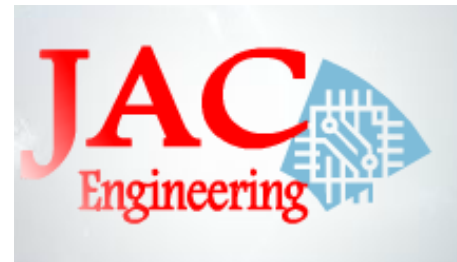
- Small assembly house - suitable for Low to Mid volume project /prototype with low design complexity.
- Located in Puchong, Kuala Lumpur Malaysia -9000 sq.ft.
- One SMT line.
- SOICs, SSOPs, QFPs, PLCC, QFN, DFN. (BGA is not possible)
- Facilities: Pick and Place Machine, Encapsulation Machines, Coiling and Reflow Ovens.
- Standard chip size component: 0603 and larger

# Electronics manufacturing services (EMS)

**ISITO**



**FLEXTRONICS** **X**



**CHESTRONICS**™  
WE ARE WIRE HARNESS MANUFACTURER

**GIDA Industries**

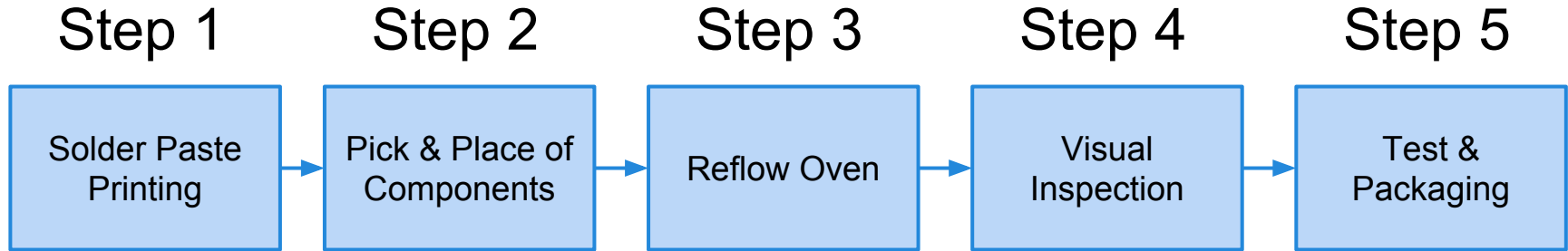


# Electronics manufacturing services (EMS)



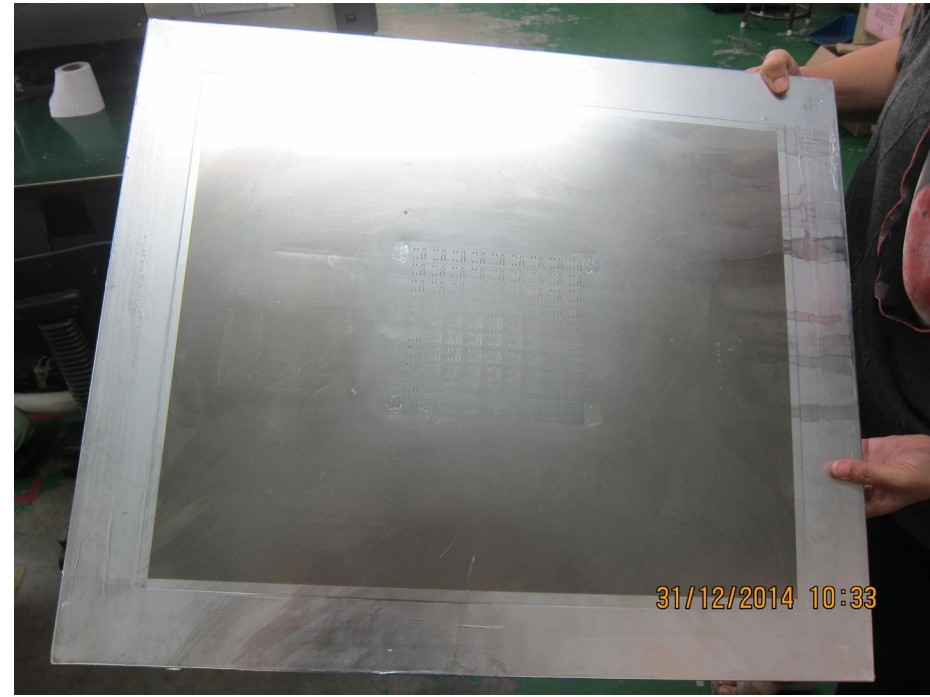
**aaco**  
TECHNOLOGIES

# PCB Production And Assembly Flow



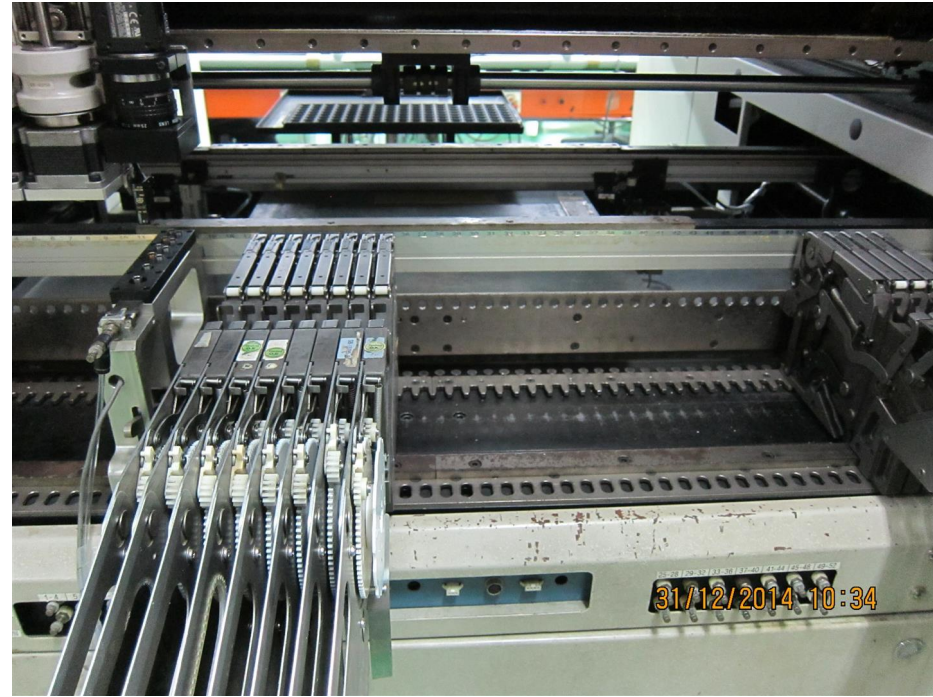


# Step 1 - Solder Paste Printing





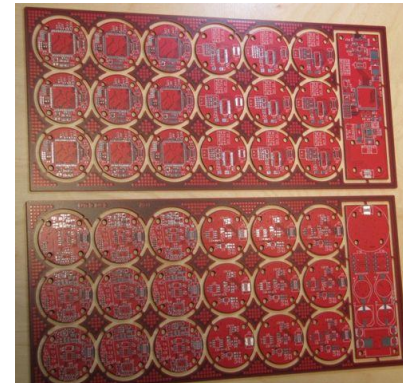
# Step 2 - Pick & Place of Components



# Step 2 - Pick & Place of Components (con't)



Jig to hold PCB



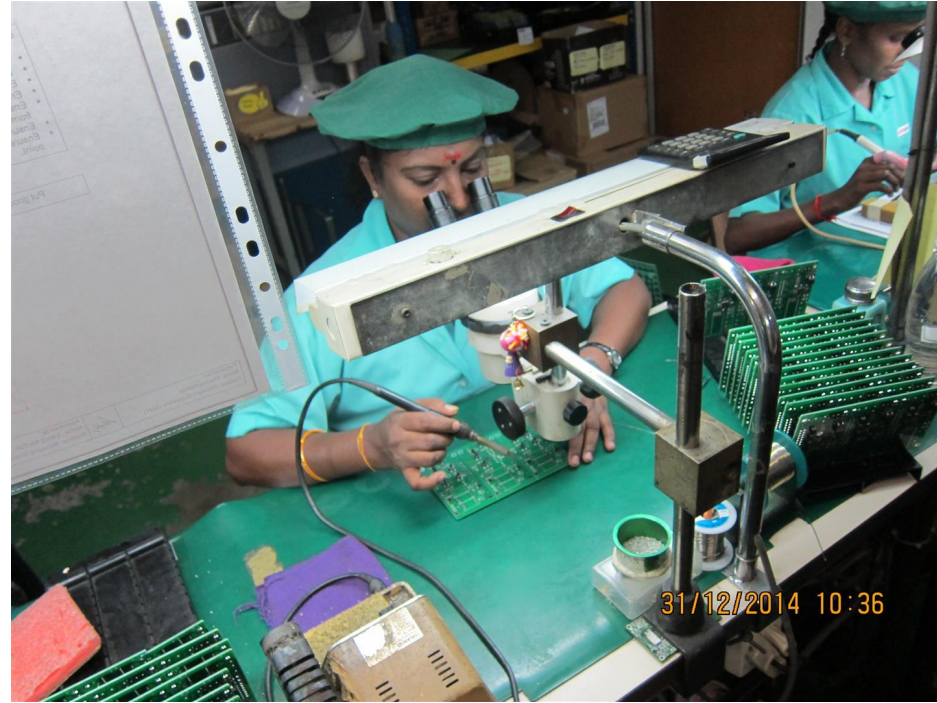
Panelize PCB

# Step 3 - Reflow Oven





# Step 4 - Visual Inspection

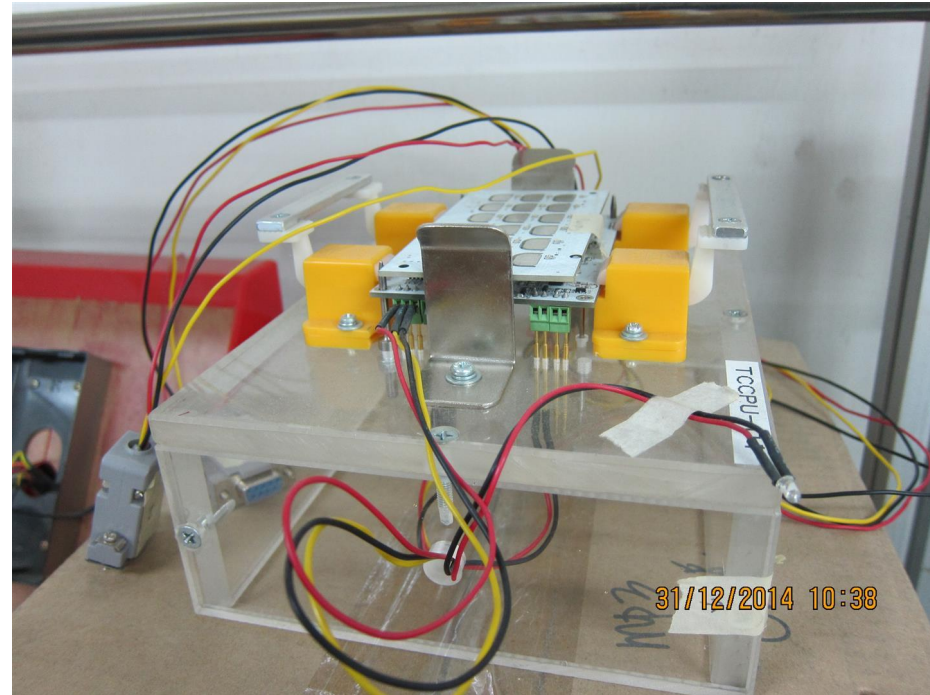
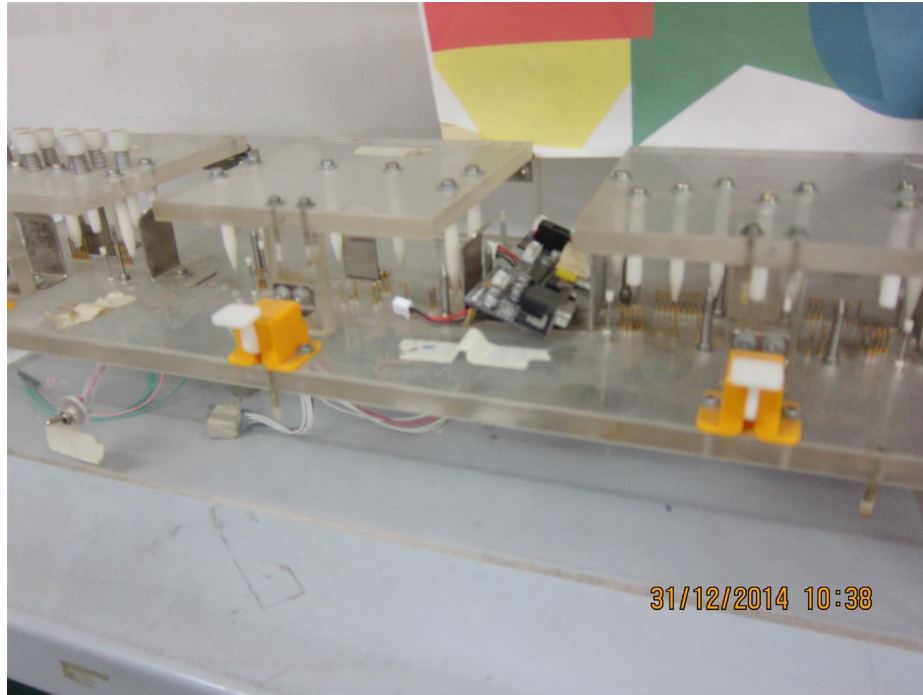


# Step 5 - Test And Packaging



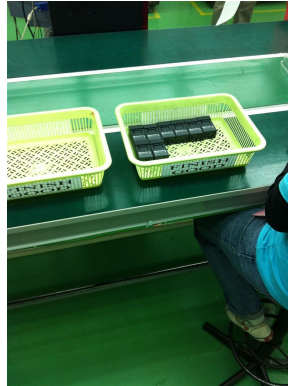
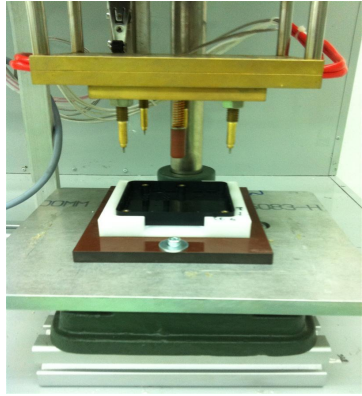


## Step 5 - Test And Packaging (Cont')





# Mechanical Assembly



# Test Reports & Product Certification

